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December 2014

FCD2250N80Z

N-Channel SuperFET® II MOSFET

800 V, 2.6 A, 2.25 Ω

Features

- $R_{DS(on)} = 1.8 \Omega (Typ.)$
- Ultra Low Gate Charge (Typ. Q_g = 11 nC)
- Low E_{oss} (Typ. 1.1 uJ @ 400V)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 51 pF)
- · 100% Avalanche Tested
- · RoHS Compliant
- · ESD Improved Capability

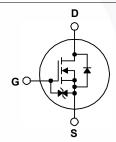
Applications

- · AC DC Power Supply
- · LED Lighting

Description

SuperFET[®] II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as Audio, Laptop adapter, Lighting, ATX power and industrial power applications.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter			Unit
V _{DSS}	Drain to Source Voltage			800	V
V _{GSS}	Cata to Source Voltage	- DC	/	±20	V
	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	_ v
I _D	Drain Current	- Continuous (T _C = 25°C)		2.6	^
	Drain Current	- Continuous (T _C = 100°C)		1.7	A
I _{DM}	Drain Current	- Pulsed	(Note 1)	6.5	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		21.6	mJ	
I _{AR}	Avalanche Current		(Note 1)	0.52	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	0.39	mJ
al/al4	MOSFET dv/dt			100	1//
dv/dt	Peak Diode Recovery dv/dt (Note 3)		20	V/ns	
Б	Daniel Biarination	(T _C = 25°C)		39	W
P_D	Power Dissipation - Derate Above 25°C			0.31	W/°C
T _J , T _{STG}	Operating and Storage Temperatur	Operating and Storage Temperature Range			οС
T _L	Maximum Lead Temperature for So	oldering, 1/8" from Case for 5 Se	econds	300	οС

Thermal Characteristics

Symbol	Parameter	FCD2250N80Z	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	3.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	100	- C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCD2250N80Z	FCD225080Z	DPAK	Tape and Reel	330 mm	16 mm	2500 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	lest Conditions	win.	ıyp.	wax.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	800	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C	-	0.85	-	V/°C
1	Zero Gate Voltage Drain Current	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	25	
IDSS	Zero Gate Voltage Drain Current	$V_{DS} = 640 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	250	μА
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±10	μА

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_{D} = 0.26$ mA	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 1.3 \text{ A}$	-	1.87	2.25	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 1.3 \text{ A}$	-	2.28	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	1001/1/	-\	440	585	pF
C _{oss}	Output Capacitance	V _{DS} = 100 V, V _{GS} = 0 V, f = 1 MHz	-	16	22	pF
C _{rss}	Reverse Transfer Capacitance	- 1 - 1 WILLS	-	0.75	-	pF
C _{oss}	Output Capacitance	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	8.4	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 480 V, V _{GS} = 0 V	-	51	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 640 V, I _D = 2.6 A,	-	11	14	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	2.2	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	4.3	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	2.8	-	Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time		-	11	32	ns
t _r		$V_{DD} = 400 \text{ V}, I_D = 2.6 \text{ A},$	-	6.7	23	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$	- /	26	62	ns
t _f	Turn-Off Fall Time	(Note 4)	-	8.7	27	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	2.6	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	6.5	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 2.6 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_{SD} = 2.6 \text{ A},$	-	260	-	ns
Q _{rr}	Reverse Recovery Charge dI _F /dt = 100 A/μs	-	2.2	-//	μС

Notes:

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2. I_{AS} = 0.52 A, R_G = 25 Ω , starting T_J = 25°C
- 3. I $_{SD} \le 2.6$ A, di/dt ≤ 200 A/µs, V $_{DD} \le$ BV $_{DSS}$, starting T $_{J}$ = $25^{\circ}C$
- 4. Essentially independent of operating temperature typical characteristic.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

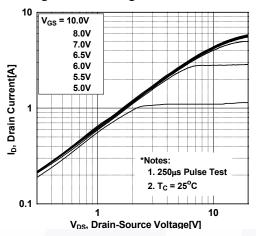


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

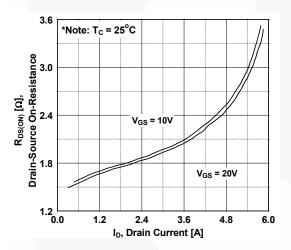


Figure 5. Capacitance Characteristics

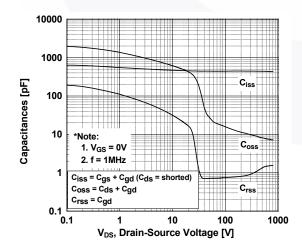


Figure 2. Transfer Characteristics

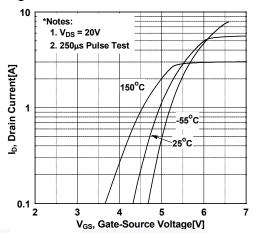


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

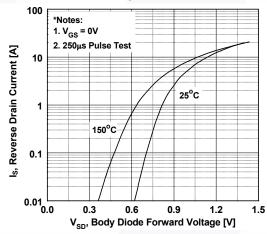
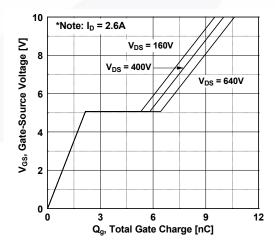


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

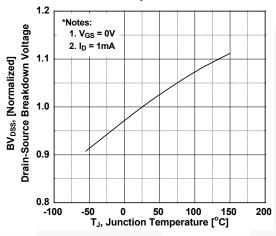


Figure 9. Maximum Safe Operating Area

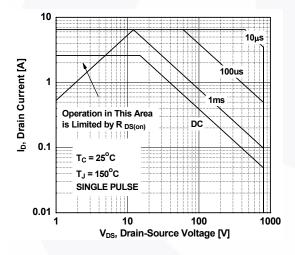


Figure 11. Eoss vs. Drain to Source Voltage

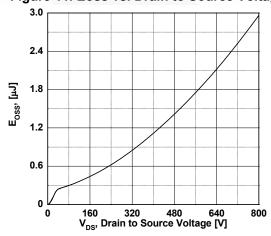


Figure 8. On-Resistance Variation vs. Temperature

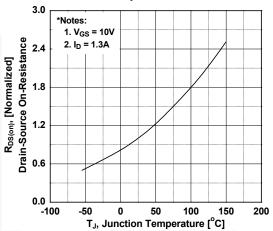
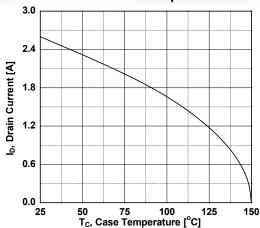
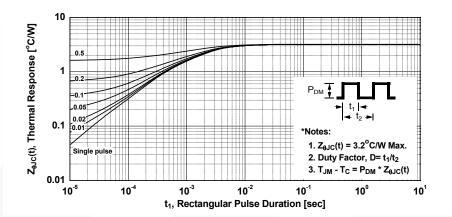


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



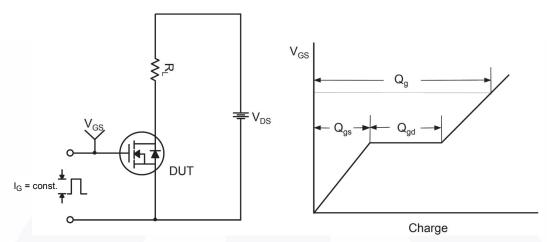


Figure 13. Gate Charge Test Circuit & Waveform

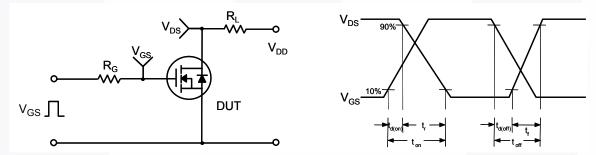


Figure 14. Resistive Switching Test Circuit & Waveforms

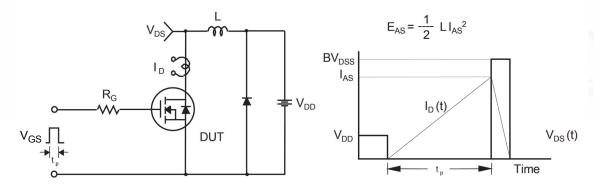


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

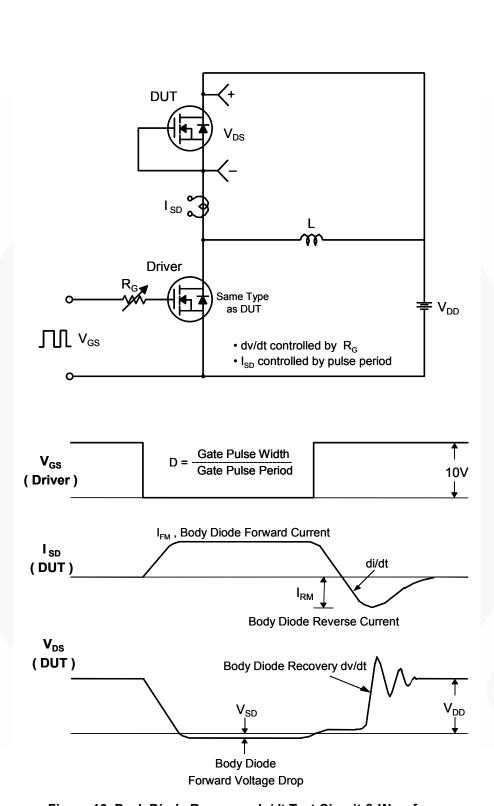


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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